

AMENDMENTS

Please amend the application as follows:

In the Specification

Please amend the paragraph beginning at page 10, line 26 as follows:

Alternative methods of preventing the PPV layer 17₁₆ from entering recesses 21₂₂ and 23₂₄ can be used and FIG. 6 illustrates a first alternative. The surface of contact region 19-1 is shown on an enlarged scale. The ITO contact region 12-2 is treated to provide a surface roughness such that a series of protuberances 25₂₆ are formed in the ITO layer. During fabrication of the device, no repellent layer need be used and the layer 16-1 of light emissive material may extend over the interior surface of recess 21₂₂. However, the protuberances 26 extend through the layer 16-1 and form an electrical connection with the metallic cathode 17-1. The protuberances 26 can be produced by roughening a thick ITO layer 12 for example of thickness 200-500 nm and etching it in the recess 18-1 only. A suitable wet etchant is ferric chloride and hydrochloric acid mixture, although a dry etch HCl/HBr mixture could be used. Another method of roughening is to deposit a metal such as aluminium on the ITO layer 12 and pattern it in the region of the recess. This will be quite grainy and rough, and will spike and hillock during the deposition of the oxide layer 15, or by means of a thermal treatment at 300-400C.

In the Drawings

Attached hereto is a replacement sheet for FIG. 6 and FIG. 7 to be entered that complies with 37 CFR 1.121 (d).